

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L2	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L3	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L4	929	redistribution adj layer and "257"\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L5	368	redistribution adj layer and "257"\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L6	9	L5 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L7	17	L5 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43
L8	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L9	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L10	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L11	16	bump same (wiring layer metallizaton) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L12	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L13	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L14	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L15	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43

EAST Search History

L16	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L17	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L18	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L19	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L20	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L21	1	"5,854,513".pn.,	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L22	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L23	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L24	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L25	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L26	0	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L27	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L28	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43

EAST Search History

L29	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L30	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L31	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L32	929	redistribution adj layer and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L33	368	redistribution adj layer and "257"/\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L34	9	L33 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L35	17	L33 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43
L36	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L37	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L38	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L39	16	bump same (wiring layer metallizaton) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L40	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L41	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L42	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L43	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43

EAST Search History

L44	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L45	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L46	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L47	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L48	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L49	1	"5,854,513".pn.,.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L50	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L51	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L52	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L53	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L54	0	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L55	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L56	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43

EAST Search History

L57	2290	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/22 10:43
L58	228	L57 and probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L59	14	("20040036170" "4051508" "5646439" "5854513" "6511901" "6590295" "6864562").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L60	621	wire with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L61	2	"6844631".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L62	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L63	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L64	9	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L65	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L66	1	"6,844,631".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L67	18	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN. OR ("6844631").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L68	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L69	174	bump with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L70	46	("3380155" "3812521" "4087314" "4154877" "4447857" "4792532" "4845354" "4948754" "5010389" "5036163" "5187020" "5281684" "5289631" "5299729" "5306664" "5354955" "5436197" "5451715" "5480834" "5504036" "5517127" "5541524" "5559054").PN. OR ("6204074").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L71	128	bond near2 wire with copper near2 pad	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L72	18	("20030197289" "20040036170" "40 51508" "5646439" "5854513" "6511 901" "6590295" "6844631" "686456 2").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L73	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L74	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L75	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L76	929	redistribution adj layer and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L77	368	redistribution adj layer and "257"/\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L78	9	L77 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L79	17	L77 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43

EAST Search History

L80	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L81	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L82	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L83	16	bump same (wiring layer metallizaton) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L84	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L85	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L86	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L87	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43
L88	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L89	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L90	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L91	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L92	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L93	1	"5,854,513".pn.,	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L94	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L95	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L96	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L97	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L98	0	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L99	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L100	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L101	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L102	929	redistribution adj layer and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L103	621	wire with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L104	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L105	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L106	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L107	128	bond near2 wire with copper near2 pad	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L108	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43

EAST Search History

L109	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L110	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L111	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L112	368	redistribution adj layer and "257"/\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L113	17	L112 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43
L114	1	"6,844,631".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L115	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L116	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L117	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L118	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L119	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L120	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L121	2290	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/22 10:43

EAST Search History

L122	46	("3380155" "3812521" "4087314" "4154877" "4447857" "4792532" "4845354" "4948754" "5010389" "5036163" "5187020" "5281684" "5289631" "5299729" "5306664" "5354955" "5436197" "5451715" "5480834" "5504036" "5517127" "5541524" "5559054").PN. OR ("6204074").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L123	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L124	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L125	16	bump same (wiring layer metallization) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L126	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L127	0	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L128	9	L112 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L129	228	L121 and probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L130	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L131	14	("20040036170" "4051508" "564643 9" "5854513" "6511901" "6590295" " 6864562").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L132	9	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L133	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43

EAST Search History

L134	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L135	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L136	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L137	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L138	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43
L139	174	bump with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L140	18	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN. OR ("6844631").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L141	2	"6844631".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L142	1	"5,854,513".pn.,	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L143	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L144	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L145	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43

EAST Search History

L146	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L147	929	redistribution adj layer and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L148	368	redistribution adj layer and "257"/\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L149	9	L148 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L150	17	L148 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43
L151	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L152	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L153	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L154	16	bump same (wiring layer metallizaton) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L155	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L156	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L157	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L158	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43
L159	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L160	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L161	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L162	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L163	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L164	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L165	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L166	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L167	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L168	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L169	0	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L170	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L171	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L172	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L173	929	redistribution adj layer and "257"\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L174	621	wire with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43

EAST Search History

L175	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L176	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L177	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L178	128	bond near2 wire with copper near2 pad	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L179	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L180	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L181	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L182	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L183	368	redistribution adj layer and "257"/\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L184	17	L183 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43
L185	1	"6,844,631".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L186	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L187	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L188	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L189	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L190	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L191	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L192	2290	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/22 10:43
L193	46	("3380155" "3812521" "4087314" "4154877" "4447857" "4792532" "4845354" "4948754" "5010389" "5036163" "5187020" "5281684" "5289631" "5299729" "5306664" "5354955" "5436197" "5451715" "5480834" "5504036" "5517127" "5541524" "5559054").PN. OR ("6204074").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L194	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L195	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L196	16	bump same (wiring layer metallization) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L197	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L198	0	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L199	9	L183 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L200	228	L192 and probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L201	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L202	14	("20040036170" "4051508" "5646439" "5854513" "6511901" "6590295" "6864562").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L203	9	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L204	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L205	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L206	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L207	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L208	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L209	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43
L210	174	bump with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L211	18	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN. OR ("6844631").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L212	2	"6844631".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L213	1	"5,854,513".pn.,	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L214	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43

EAST Search History

L215	18	("20030197289" "20040036170" "4051508" "5646439" "5854513" "6511901" "6590295" "6844631" "6864562").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L216	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L217	0	wafer with passivation with nitride with thikcness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L218	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L219	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L220	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L221	0	trace with UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L222	2290	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/22 10:43
L223	5	bump with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L224	1	"5,854,513".pn,.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L225	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L226	0	trace with made with (gold au) with highly and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L227	0	redistribuiton with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L228	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L229	0	wafer with passivation with nitride with thikcness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L230	0	trace with UBM with gold with nickel with copper	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L231	1	"5,854,513".pn,.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L232	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L233	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L234	1	"6,844,631".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L235	1	"6511901".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L236	1	"5,854,513".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L237	1	"6,287,893".pn.	USPAT; EPO	OR	ON	2008/01/22 10:43
L238	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L239	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L240	368	redistribution adj layer and "257"/\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L241	9	L240 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L242	17	L240 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43
L243	46	("3380155" "3812521" "4087314" "4154877" "4447857" "4792532" "4845354" "4948754" "5010389" "5036163" "5187020" "5281684" "5289631" "5299729" "5306664" "5354955" "5436197" "5451715" "5480834" "5504036" "5517127" "5541524" "5559054").PN. OR ("6204074").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L244	16	bump same (wiring layer metallization) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L245	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L246	368	redistribution adj layer and "257"/\$. ccls.	USPAT; EPO	OR	ON	2008/01/22 10:43
L247	9	L246 and harper	USPAT; EPO	OR	ON	2008/01/22 10:43
L248	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L249	16	bump same (wiring layer metallization) with gold with copper with passivation	USPAT; EPO	OR	ON	2008/01/22 10:43
L250	4	("6864562" "5854513").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L251	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L252	2	"6844631".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L253	128	bond near2 wire with copper near2 pad	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L254	174	bump with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L255	929	redistribution adj layer and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L256	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L257	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L258	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43
L259	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L260	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L261	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L262	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L263	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L264	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L265	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L266	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L267	5	bump same (trace) with gold with highly	USPAT; EPO	OR	ON	2008/01/22 10:43
L268	6	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L269	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L270	42	trace with made with (gold au)and bump	USPAT; EPO	OR	ON	2008/01/22 10:43
L271	19	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN. OR ("6577008").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43

EAST Search History

L272	17	L246 and Elenius	USPAT; EPO	OR	ON	2008/01/22 10:43
L273	14	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6420787").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L274	2	"20050121804".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L275	3	("20040130029" "20050145959" "6844631").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L276	14	("20040036170" "4051508" "564643 9" "5854513" "6511901" "6590295" 6864562").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L277	9	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L278	106	UBM with au with ni with cu	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L279	25	wafer with passivation with nitride with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L280	75	trace with bump with wir\$3 adj3 bond\$3	USPAT; EPO	OR	ON	2008/01/22 10:43
L281	18	("4475191" "5506499" "5514892" "5554940" "6144100" "6232662" "6303459" "6373143" "6451681").PN. OR ("6844631"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 10:43
L282	228	L222 and probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L283	621	wire with bond with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43

EAST Search History

L284	929	redistribution adj layer and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L285	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L286	1386	redistribution adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 10:43
L287	2955	((silicon semiconduct\$3) and (bump solder adj ball) and (bond\$3 wir\$3)).clm.	US-PGPUB	OR	ON	2008/01/22 10:43
L288	97	(metallizat\$3 and (silicon semiconduct\$3) and (bump solder adj ball) and (bond\$3 wir\$3)).clm.	US-PGPUB	OR	ON	2008/01/22 10:43
L289	0	"5719422".pn.	US-PGPUB	OR	ON	2008/01/22 10:43
L290	1	"5719422".pn.	US-PGPUB; USPAT	OR	ON	2008/01/22 10:43
L291	0	pertos\$4.xa.	US-PGPUB; USPAT	OR	ON	2008/01/22 10:43
L292	0	pertr\$5.xa.	US-PGPUB; USPAT	OR	ON	2008/01/22 10:43
L293	0	petrok\$5.xa.	US-PGPUB; USPAT	OR	ON	2008/01/22 10:43
L294	2	petrosk\$3.xa.	US-PGPUB; USPAT	OR	ON	2008/01/22 10:43
L295	144	andujar.xa.	US-PGPUB; USPAT	OR	ON	2008/01/22 10:43
L296	0	(Inteposer and (IC chi die wafer) and (electrode pad contact\$3)).clm.	US-PGPUB	OR	ON	2008/01/22 10:43
L297	20833	((IC chi die wafer) and (electrode pad contact\$3)).clm.	US-PGPUB	OR	ON	2008/01/22 10:43
L298	2227	((IC chi die wafer) and (electrode pad contact\$3) and board).clm.	US-PGPUB	OR	ON	2008/01/22 10:43
L299	0	"4,994,871".pn.	US-PGPUB	OR	ON	2008/01/22 10:43
L300	1	"4994871".pn.	US-PGPUB; USPAT	OR	ON	2008/01/22 10:43